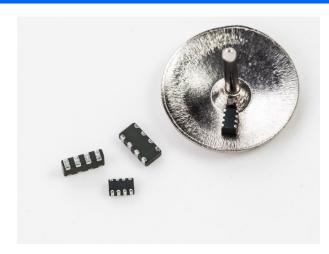




# **Surface Mount Multilayer Varistors ESD Array Series**



#### Features:

- Low Leakage Current
- Low Leakage Inductance and Fast Response
- Four Varistors in a chip
- Minimizing Crosstalk between Adjacent Circuits

## **Application Fields:**

- ESD protection
- ECU protection
- I/O Protection
- LCD Display

# **Ordering Information:**

Part Number	Working Voltage (Max.)	Breakdown Voltage	Clamping Voltage (Max.)	Leakage Current (Max.)	Insulation Resistance (Min.)	Typical Capacitance Value (1 MHz)	Tolerance of Cap.
	DC(V)	(V)	(V)	(μ <b>Α</b> )	(ΜΩ)	(pF)	(%)
MVA0508L4V005C0010N	5	24	60	1.0	10	10	± 30
MVA0612L4V018C0120N	18	28	50	1.0	10	120	± 30





#### **Product Identification:**

MLV 0402 ES 012V 0100 N T (1) (2) (3) (4) (5) (6) (7)

(1) Series Code:

MLV - Surface Mount Multilayer Varistor

MVA -- MLV Array

(2) Size Code:

Standard EIA Chip Size

(3) Application Code:

ES - Electro-static Discharge Protection

**NA** – Normal Surge Protection

**HA** – High Surge Protection

(4) Max. Working Voltage:

**012V** – 12 V

(5) Capacitance for ES Series:

**0100** - 100 pF

02R5 - 2.5 pF

Peak Current for HA/NA Series: 0100 - 100 A

(6) Capacitance Tolerance for ES Series:

 $N - \pm 30\%$ 

P - Special

(7) Packaging Code:

T - Tape & Reel

#### **Operating Temperatures:**

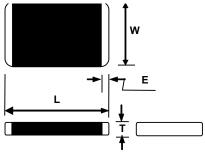
- -55°C to +85°C for size 0603 or smaller
- -55°C to +125°C for size 0805 or larger





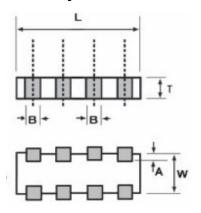
# **Shape and Dimensions:**

## **MLV Series**



	Size	L (mm)	W (mm)	T (mm)	E (mm)
	0201	0.60 ± 0.03	$0.30 \pm 0.03$	$0.30 \pm 0.03$	$0.30 \pm 0.03$
	0402	1.00 ± 0.10	0.50 ± 0.10	0.50 ± 0.10	0.25 ± 0.10
	0603	1.60 ± 0.15	$0.80 \pm 0.15$	0.90 max.	0.30 ± 0.10
	0805	$2.00 \pm 0.20$	$1.25 \pm 0.15$	1.00 max.	0.30 ± 0.10
)	1206	$3.20 \pm 0.20$	$1.60 \pm 0.15$	1.20 max.	0.50 ± 0.20
	1210	$3.20 \pm 0.20$	$2.50\pm0.20$	1.50 max.	0.50 ± 0.20
	1812	4.50 ± 0.20	$3.20 \pm 0.20$	2.00 max.	0.60 ± 0.20
	2220	5.70 ± 0.20	5.00 ± 0.20	3.00 max.	0.60 ± 0.20

## **ESD Array**



Size	0508	0612
L (mm)	2.00 ± 0.20	3.20 ± 0.20
W (mm)	1.25 ± 0.20	1.60 ± 0.15
T (mm)	0.80 max.	0.95 max.
A (mm)	0.20 ± 0.10	0.20 ± 0.10
B (mm)	0.25 ± 0.05	0.40 ± 0.15

## **Terms and Definitions:**

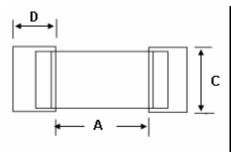
Term	Definition	
Max. Working Voltage	Maximum steady-state DC operating voltage with typical leakage current less than 50 μA at 25°C	
Varistor Voltage (BDV)	Breakdown DC voltage measured at current of 1 mA	
Max. Clamping Voltage	Maximum peak voltage across the part, measured at a specified pulse current and waveform	
Surge Current	Maximum peak current with the specified 8/20 µs waveform without damage	
Surge Shift △ V/V	The change of varistor voltage after applying the specified surge current	
Energy Absorption	Maximum energy dissipated with a specified 10/1000 μs waveform without damage	
Typical Capacitance	Capacitance measured with voltage bias less than 0.5 V <sub>RMS</sub> at 1 KHz or 1 MHz	
Nonlinear Exponentα	$\alpha = (\log (V_{1mA}/V_{0.1mA}) / \log (I_{V1mA}/I_{V0.1mA}))$	
Leakage Current	Typical leakage current at 25 °C < 50 μA; Maximum leakage 200 μA.	
Cut-off Frequency	The frequency of -3 dB insertion loss	





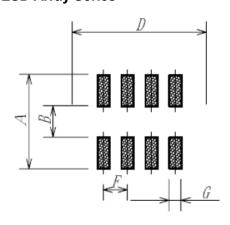
## **Recommended Land Patterns:**

## **MLV Series**



	Solder pad layout			
Size	A (mm)	C (mm)	D (mm)	
0201	0.25~0.35	0.20~0.30	0.25~0.35	
0402	0.4~0.6	0.5~0.6	0.5~0.7	
0603	0.9~1.2	0.6~1.0	0.8~1.2	
0805	1.0~1.5	1.2~1.5	1.0~1.4	
1206	1.8~2.5	1.2~1.8	1.0~1.4	
1210	1.8~2.5	2.2~3.0	1.0~1.4	
1812	2.5~3.3	2.8~3.6	1.2~1.8	
2220	3.8~4.6	4.8~5.5	1.2~1.8	

# **ESD Array Series**



Size	A (mm)	B (mm)	D (mm)	F (mm)	G (mm)
0508	2.10	0.40	2.50	0.50	0.35
0612	2.60	0.80	3.60	0.80	0.50





## **Environmental Tests:**

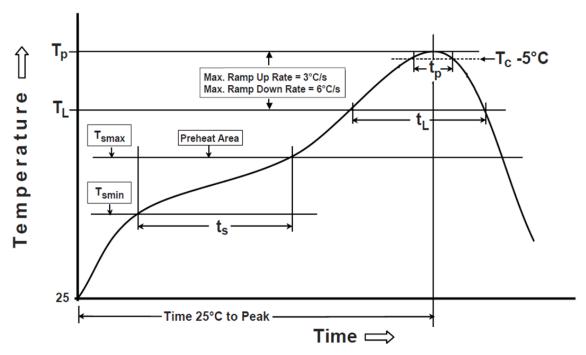
No.	Test	Requirement	Test condition	Test reference
1	Soldering heat resistance	BDV change ≤ ±10% No mechanical damage	One dip at 260°C for 5 sec.	MIL-STD-202 Method 210 IEC 60068-2-20
2	Solderability	New solder coverage ≥ 80%	One dip at 255°C for 5 sec. Non-active flux	MIL-STD-202 Method 208 IEC 60068-2-20
3	Maximum surge current	BDV change ≤ ±10% No mechanical damage	100 pulses of 8/20 µs with maximum surge current and 30 sec. interval at 25°C and 30 ~ 65% RH	CECC 42000 IEC 1051-1 Test 4.5
4	Maximum surge energy	BDV change ≤ ±10% No mechanical damage	100 pulses of 10/1000 μs with maximum surge current and 90 sec. interval at 25°C and 30 ~ 65% RH	CECC 42000
5	Thermal cycling	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	5 cycles between -40°C and 125°C with 30 min. dwell time at the temperature extremes and 60 min. dwell time at 25°C	CECC 42000 IEC 60068-2-14
6	Low temperature resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	1000 hr at -50°C	IEC 60068-2-1
7	Low temperature load resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	1000 hr at -50°C with working voltage applied	IEC 60068-2-1
8	High temperature resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	1000 hr at 150°C	MIL-STD-202 Method 108 CECC 42000
9	High temperature load resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	1000 hr at 85°C with working voltage applied	CECC 42000
10	Humidity resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	500 hr at 40°C and 90 ~ 95% RH	MIL-STD-202 Method 103 IEC 60068-2-3 CECC 42000;
11	Humidity load resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	500 hr at 40°C and 90 ~ 95% RH with working voltage applied	MIL-STD-202 Method 103 IEC 60068-2-3 CECC 42000
12	ESD contact test*	Varistor voltage change > 115% working voltage	Contact electrostatic discharge 100 times with 1 second intervals at 8 KV (Level 4 ) and polarity: +,-	IEC 61000-4-2
13	ESD air test*	Varistor voltage change > 115% working voltage	Air contact electrostatic discharge 100 times with 1 second intervals at 15 KV (Level 4 ) and polarity:+,-	IEC 61000-4-2

<sup>\*</sup> For ES series only.





# **Soldering Temperature Profile:**



Profile Feature	Pb-Free Assembly		
Preheat/Soak Temperature Min (T <sub>smin</sub> ) Temperature Max(T <sub>smax</sub> ) Time(t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	150°C 200°C 60~120 seconds		
Ramp-uprate (T <sub>L</sub> to T <sub>p</sub> )	3°C/second max.		
$\begin{array}{c} \text{Liquidous temperature}(T_L) \\ \text{Time}(t_L) \text{ maintained above } T_L \end{array}$	217°C 60~150 seconds		
Peak package body temperature (T <sub>p</sub> )	260°C		
Time $(t_p)^*$ within 5°C of the specified classification temperature $(T_c)$	30 seconds *		
Ramp-down rate (Tp to TL)	6°C/second max.		
Time 25°C to peak temperature	8 minutes max.		
* Tolerance for peak profile temperature (T <sub>D</sub> ) is defined as a supplier minimum and a user maximum			





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